

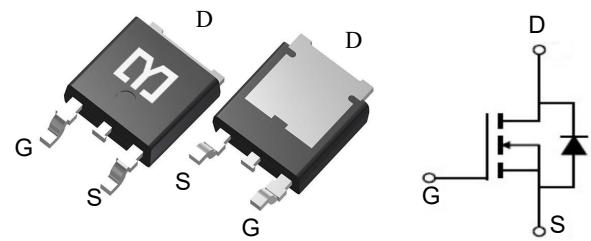
## General Description

The MY10N20D is silicon N-CH Enhanced VDMOSFETs is obtained by the self-aligned planar Technology which reduce the conduction loss, improve switching performance and enhance the avalanche energy. The transistor can be used in various power switching circuit for system miniaturization and higher efficiency.



## Features

V <sub>DSS</sub>	200	V
I <sub>D</sub>	10	A
P <sub>D</sub> (T <sub>C</sub> =25°C)	74	W
R <sub>DS(ON)</sub> (at V <sub>GGS</sub> =4.5V)	320	mΩ



## Application

- Uninterruptible Power Supply(UPS)
- Power Factor Correction (PFC)

## Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MY10N20D	TO-252-2L	MY10N20D	2500

## Absolute Maximum Ratings (T<sub>c</sub>=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (V <sub>GS</sub> = 0V)	V <sub>DSS</sub>	200	V
Continuous Drain Current	I <sub>D</sub>	10	A
Pulsed Drain Current	I <sub>DM</sub>	36	A
Gate-Source Voltage	V <sub>GSS</sub>	±20	V
Single Pulse Avalanche Energy	E <sub>AS</sub>	100	mJ
Avalanche Current	I <sub>AR</sub>	7.5	A
Repetitive Avalanche Energy	E <sub>AR</sub>	8.1	mJ
Power Dissipation (T <sub>c</sub> = 25°C)	P <sub>D</sub>	74	W
Thermal Resistance, Junction-to-Case	R <sub>thJC</sub>	1.7	°C/W
Thermal Resistance, Junction-to-Ambient	R <sub>thJA</sub>	62.5	
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55~+150	°C

Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	200	222	--	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 200\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 25^\circ\text{C}$	--	--	5	$\mu\text{A}$
		$V_{\text{DS}} = 160\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 125^\circ\text{C}$	--	--	100	
Gate-Source Leakage	$I_{\text{GSS}}$	$V_{\text{GS}} = \pm 20\text{V}$	--	--	$\pm 100$	nA
Gate-Source Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	2	2.9	4	V
Drain-Source On-Resistance (Note3)	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 2.5\text{A}$	--	320	380	$\text{m}\Omega$
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 25\text{V}, f = 1.0\text{MHz}$	--	684	--	$\text{pF}$
Output Capacitance	$C_{\text{oss}}$		--	103	--	
Reverse Transfer Capacitance	$C_{\text{rss}}$		--	37	--	
Total Gate Charge	$Q_g$	$V_{\text{DD}} = 160\text{V}, I_D = 5.0\text{A}, V_{\text{GS}} = 10\text{V}$	--	23	--	$\text{nC}$
Gate-Source Charge	$Q_{\text{gs}}$		--	2.5	--	
Gate-Drain Charge	$Q_{\text{gd}}$		--	9	--	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 100\text{V}, I_D = 5.0\text{A}, R_G = 25\Omega$	--	12	--	$\text{ns}$
Turn-on Rise Time	$t_r$		--	22	--	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		--	50	--	
Turn-off Fall Time	$t_f$		--	48	--	
Continuous Body Diode Current	$I_s$	$T_C = 25^\circ\text{C}$	--	--	10	$\text{A}$
Pulsed Diode Forward Current	$I_{\text{SM}}$		--	--	36	
Body Diode Voltage	$V_{\text{SD}}$	$T_J = 25^\circ\text{C}, I_{\text{SD}} = 5\text{A}, V_{\text{GS}} = 0\text{V}$	--	--	1.4	V
Reverse Recovery Time	$t_{\text{rr}}$	$V_{\text{GS}} = 0\text{V}, I_s = 5\text{A}, dI_F/dt = 100\text{A}/\mu\text{s}$	--	190	--	$\text{ns}$
Reverse Recovery Charge	$Q_{\text{rr}}$		--	1.7	--	

## Notes

- Repetitive Rating: Pulse width limited by maximum junction temperature
- $I_{\text{AS}} = 3\text{A}, V_{\text{DD}} = 50\text{V}, R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$
- Pulse Test: Pulse width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 1\%$

### Typical Characteristics

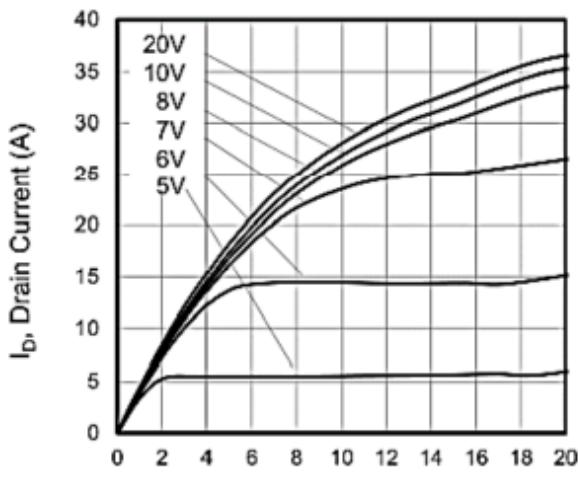


Figure 1. Output Characteristics ( $T_J = 25^\circ\text{C}$ )

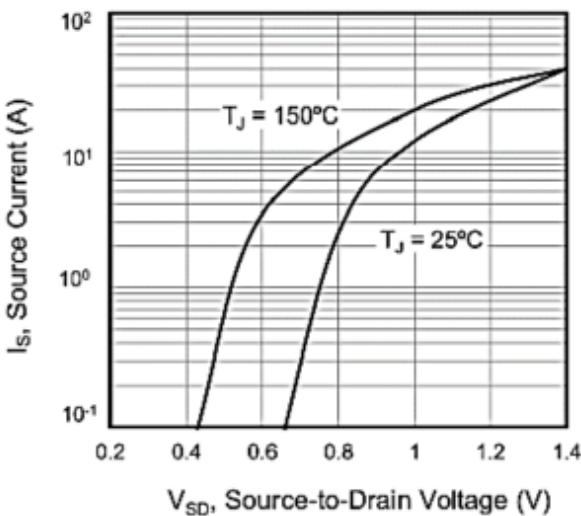


Figure 2. Body Diode Forward Voltage

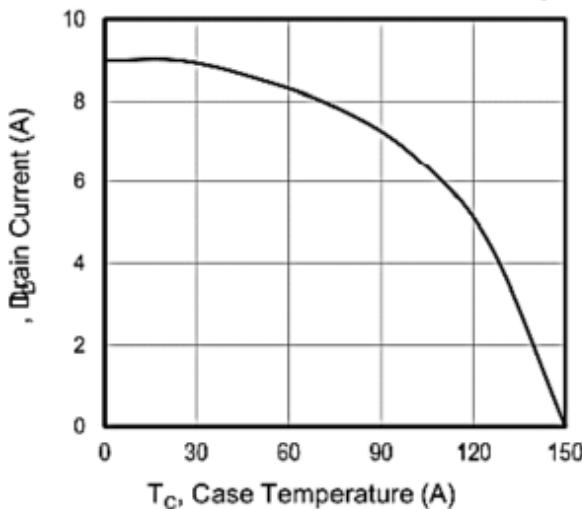


Figure 3. Drain Current vs. Temperature

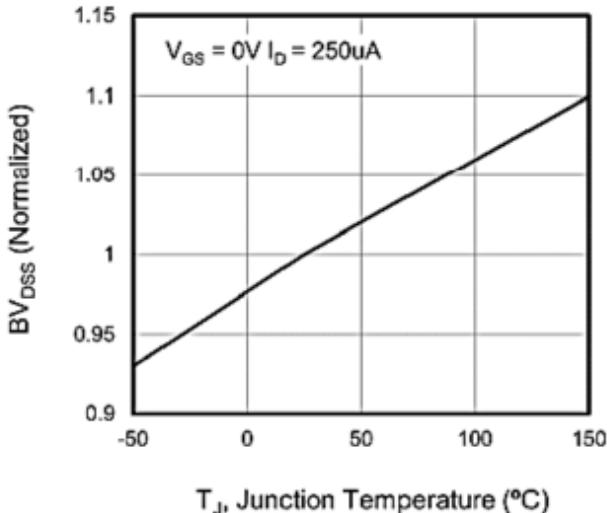


Figure 4.  $BV_{DSS}$  Variation vs. Temperature

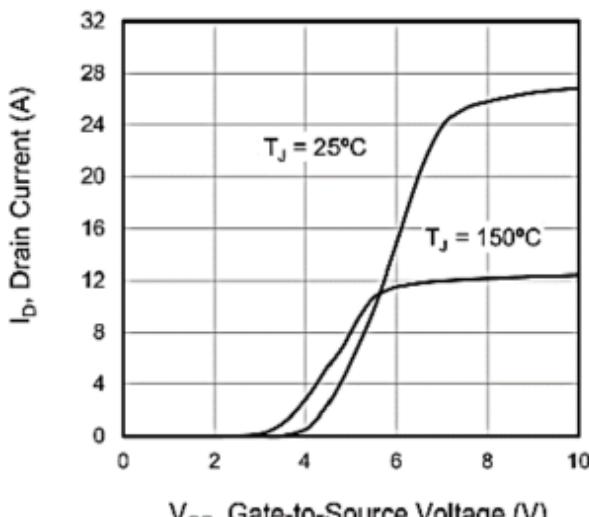


Figure 5. Transfer Characteristics

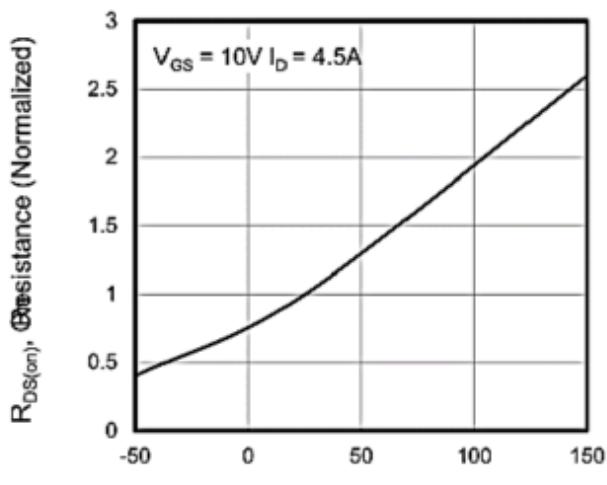


Figure 6. On-Resistance vs. Temperature

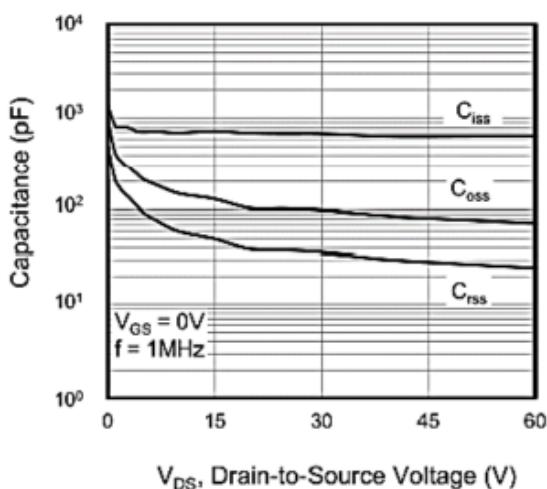


Figure 7. Capacitance

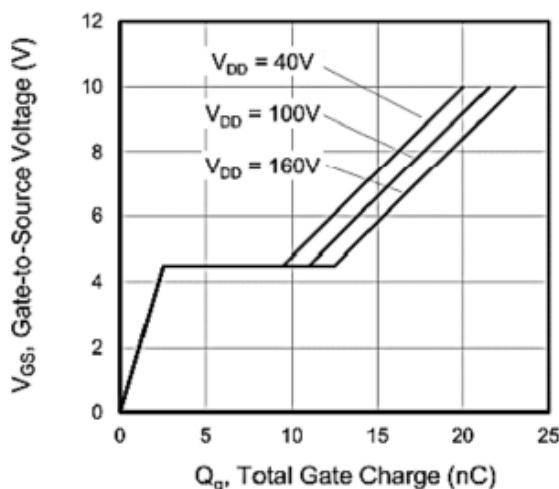


Figure 8. Gate Charge

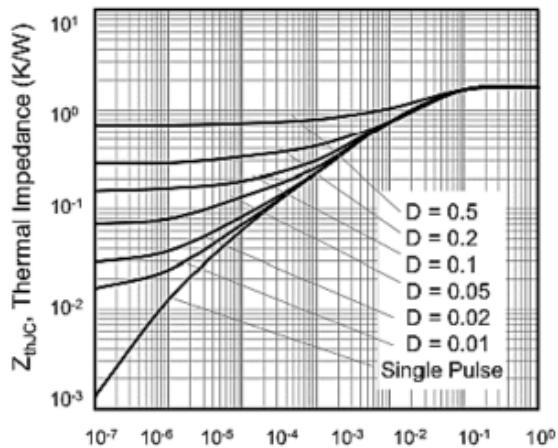
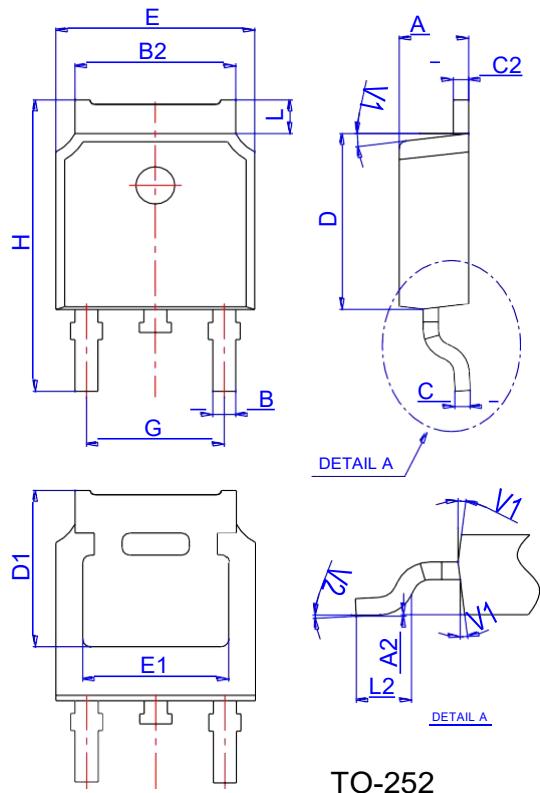


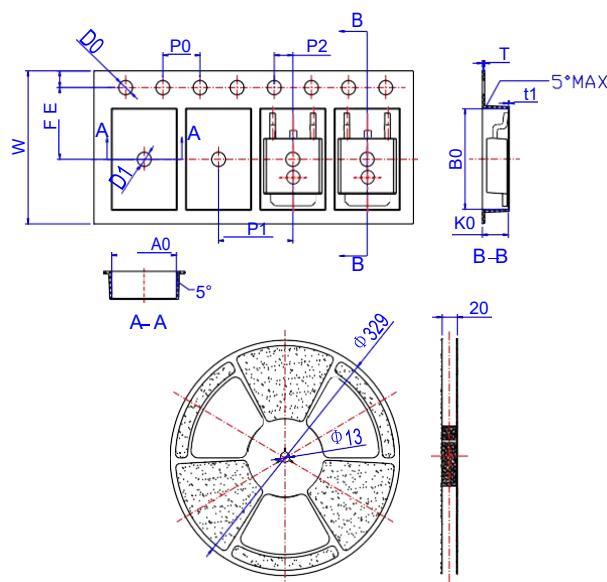
Figure 10. Transient Thermal Impedance

## Package Mechanical Data-TO-252-JQ Single



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

## Reel Specification-TO-252



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
W	15.90	16.00	16.10	0.626	0.630	0.634
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
D0	1.40	1.50	1.60	0.055	0.059	0.063
D1	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
A0	6.85	6.90	7.00	0.270	0.271	0.276
B0	10.45	10.50	10.60	0.411	0.413	0.417
K0	2.68	2.78	2.88	0.105	0.109	0.113
T	0.24		0.27	0.009		0.011
t1	0.10			0.004		
10P0	39.80	40.00	40.20	1.567	1.575	1.583